

# HFA40HF60

PD-20381D

## Ultrafast, Soft Recovery Diode Thru-Hole (TO-254AA) 600V, 22A

### Features

- Single diode configuration
- Reduced RFI and EMI
- Reduced snubbing
- Extensive characterization of recovery parameters
- Hermetic package
- Surface mount

### Product Summary

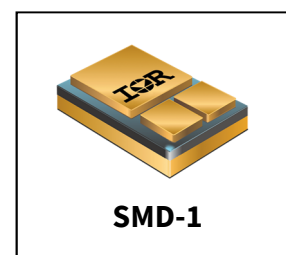
- $V_R$  : 600V
- $V_F$  : 1.75V
- $Q_{rr}$  : 190nC
- $di_{(rec)M}/dt$  : 270A/ $\mu$ s

### Potential Applications

- DC-DC converter
- Motor drives

### Product Validation

Qualified according to MIL-PRF-19500 for space applications



### Description

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and  $di/dt$  simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motor drives and other applications where switching losses are significant portion of the total losses.

### Ordering Information

**Table 1**      **Ordering options**

Part number	Package	Screening Level
HFA40HF60	SMD-1	COTS
HFA40HF60SCV	SMD-1	JANTXV-equivalent
HFA40HF60SCX	SMD-1	JANTX-equivalent
HFA40HF60SCS	SMD-1	S-level

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**Absolute Maximum Ratings****1 Absolute Maximum Ratings****Table 2 Absolute Maximum Ratings**

Symbol	Parameter	Value	Unit
$V_R$	DC Reverse Voltage	600	V
$I_F$	Continuous Forward Current, $T_C = 100\text{ }^{\circ}\text{C}$ <sup>1</sup>	22	A
$I_{FSM}$	Single pulse Forward Current, $T_C = 25^{\circ}\text{C}$ <sup>2</sup>	225	A
$P_D @ T_C = 25^{\circ}\text{C}$	Maximum Power Dissipation	83	W
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
Wt	Weight	2.6 (Typical)	g

<sup>1</sup> DC = 50% rect. wave<sup>2</sup> ½ sine wave, 60 Hz, Pulse width = 8.33 ms

## Device Characteristics

## 2 Device Characteristics

### 2.1 Electrical Characteristics

Table 3 Electrical Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$V_{BR}$	Cathode Anode Breakdown Voltage	600	—	—	V	$I_R = 100\mu A$
$V_F$	Forward Voltage Drop See Fig. 1	—	—	1.55	V	$I_F = 22A, T_J = -55^\circ C$
		—	1.63	1.75		$I_F = 22A, T_J = 25^\circ C$
		—	2.07	2.25		$I_F = 45A, T_J = 25^\circ C$
		—	1.52	1.64		$I_F = 22A, T_J = 125^\circ C$
$I_R$	Reverse Leakage Current See Fig. 2	—	—	10	$\mu A$	$V_R = V_R \text{ Rated}$
		—	—	1.0	mA	$V_R = 480V, T_J = 125^\circ C$
$C_T$	Junction Capacitance See Fig. 3	—	56	59	pF	$V_R = 200V$
$L_S$	Series Inductance	—	5.9	—	nH	Measured from center of cathode pad the center of anode pad

### 2.2 Dynamic Recovery Characteristics

Table 4 Dynamic Recovery Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$t_{rr1}$	Reverse Recovery Time See Fig. 5	—	60	97	ns	$T_J = 25^\circ C$
$t_{rr2}$		—	110	—		$T_J = 125^\circ C$
$I_{RRM1}$	Peak Recovery Current See Fig. 6	—	5.2	—	A	$T_J = 25^\circ C$
$I_{RRM2}$		—	8.5	—		$T_J = 125^\circ C$
$Q_{rr1}$	Reverse Recovery Charge See Fig. 7	—	190	—	nC	$T_J = 25^\circ C$
$Q_{rr2}$		—	560	—		$T_J = 125^\circ C$
$di_{(rec)M}/dt_1$	Peak Rate of Fall of Recovery Current During $t_b$ See Fig. 8	—	270	—	A/ $\mu s$	$T_J = 25^\circ C$
$di_{(rec)M}/dt_2$		—	170	—		$T_J = 125^\circ C$

### 2.3 Thermal-Mechanical Characteristics

Table 5 Thermal-Mechanical Characteristics

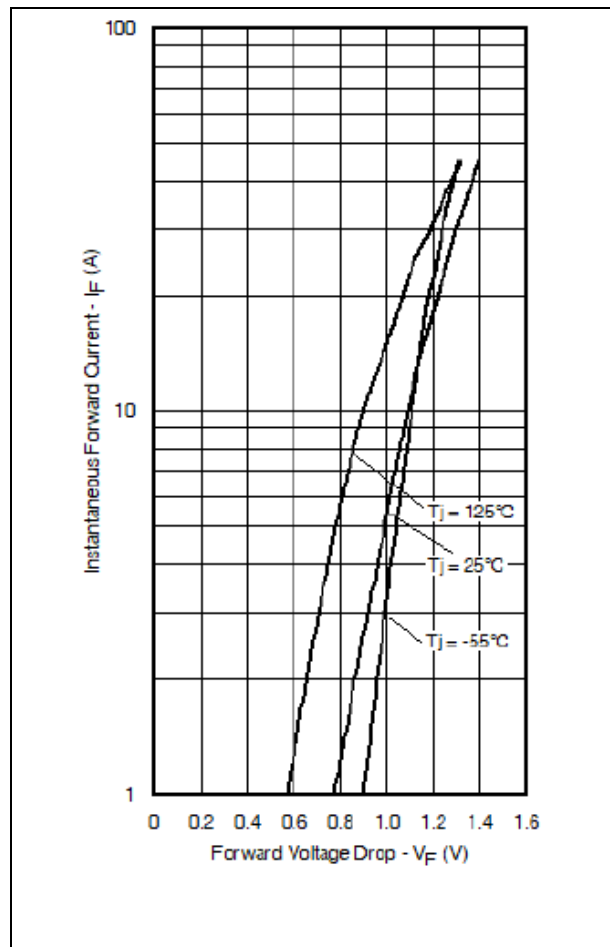
Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Junction to Case, Single Leg Conducting	—	1.5	$^\circ C/W$

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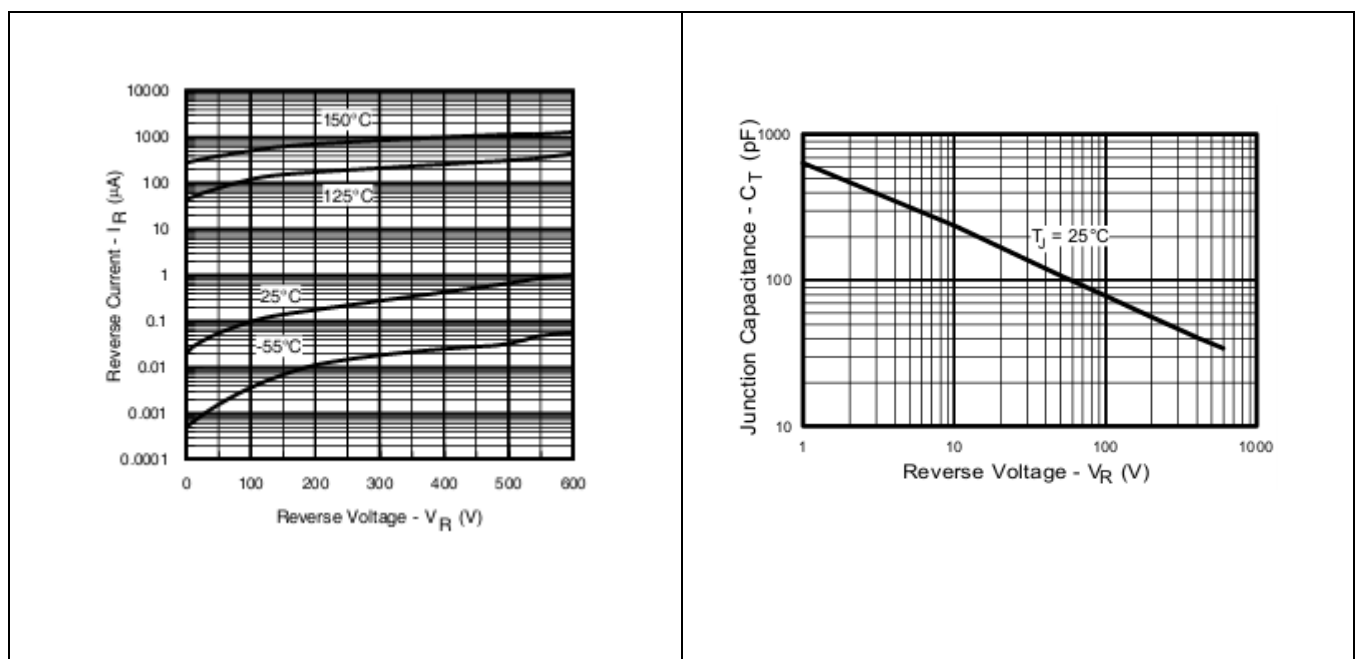
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### Electrical Characteristics Curves

## 3 Electrical Characteristics Curves



**Figure 1 Maximum Forward Voltage Drop Characteristics**



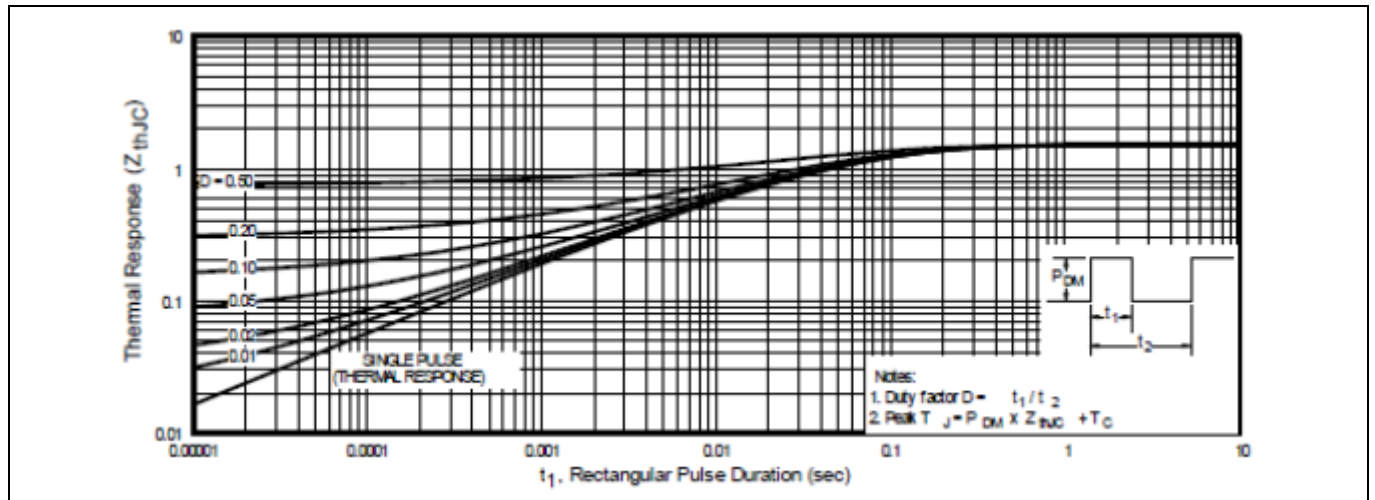
**Figure 2 Typical Values of Reverse Current Vs. Reverse Voltage**

**Figure 3 Typical Junction Capacitance Vs. Reverse Voltage**

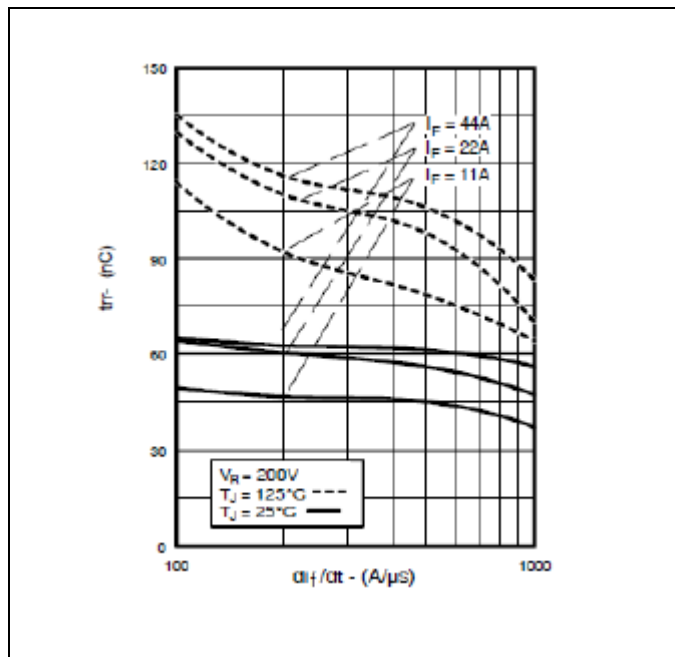
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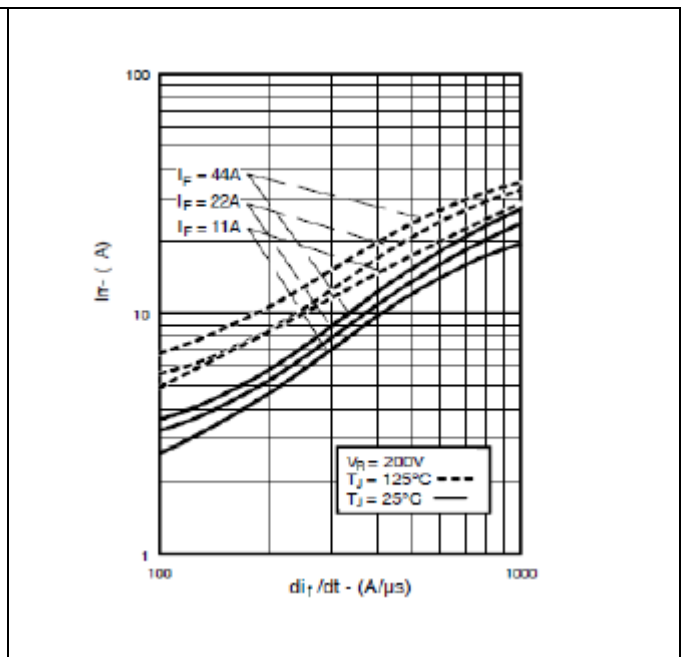
### Electrical Characteristics Curves



**Figure 4** Maximum Thermal Impedance  $Z_{thJC}$  Characteristics



**Figure 5** Typical Reverse Recovery Vs.  $di_T/dt$



**Figure 6** Typical Recovery Current Vs.  $di_T/dt$

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### Electrical Characteristics Curves

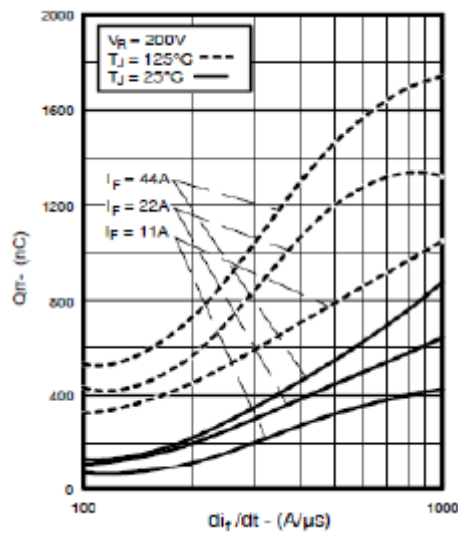


Figure 7 Typical Stored Charge Vs.  $di_f/dt$

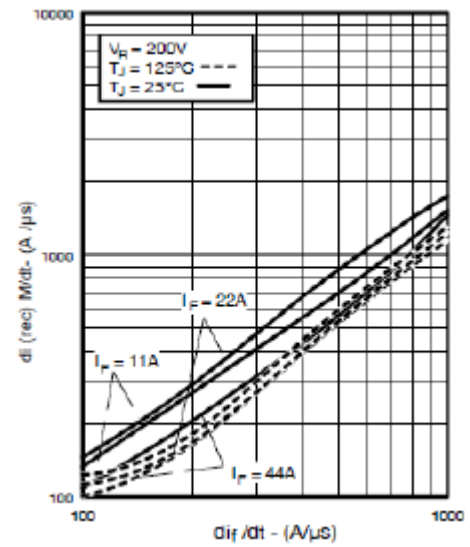


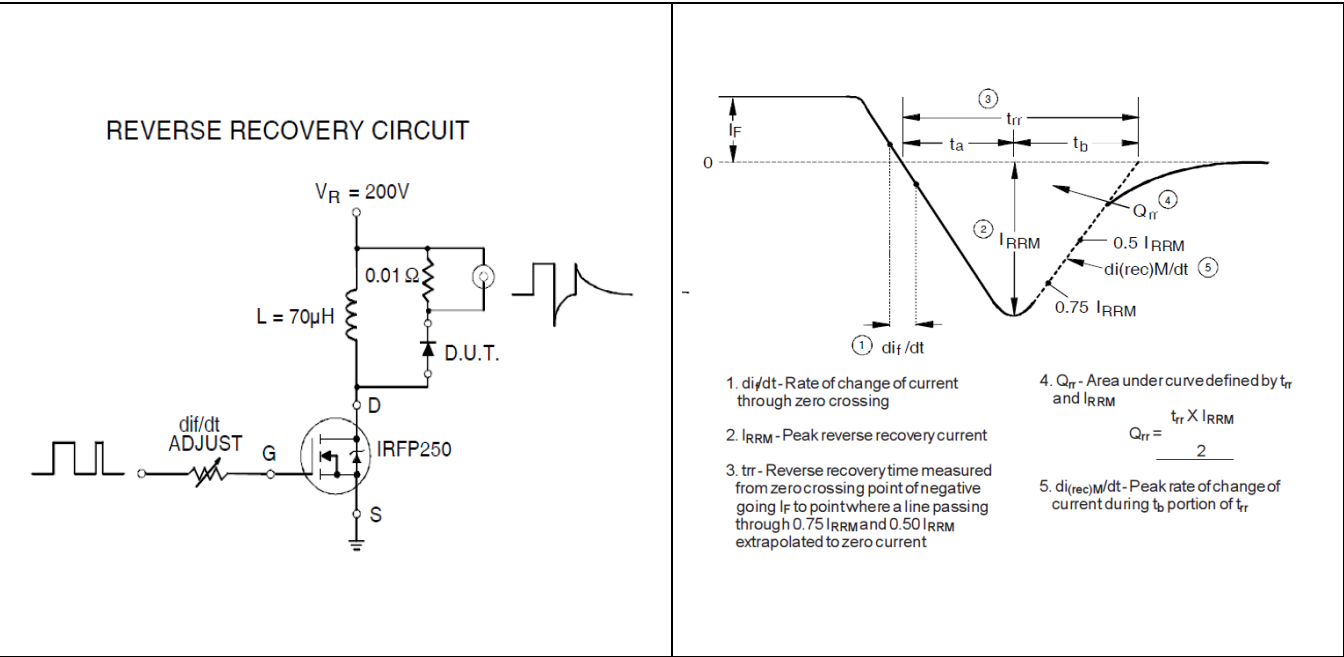
Figure 8 Typical  $di_{(rec)M}/dt$  Vs.  $di_f/dt$

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### Test Circuit

## 4 Test Circuit



**Figure 9** Reverse Recovery Parameter Test Circuit

**Figure 10** Reverse Recovery Waveform and Definitions



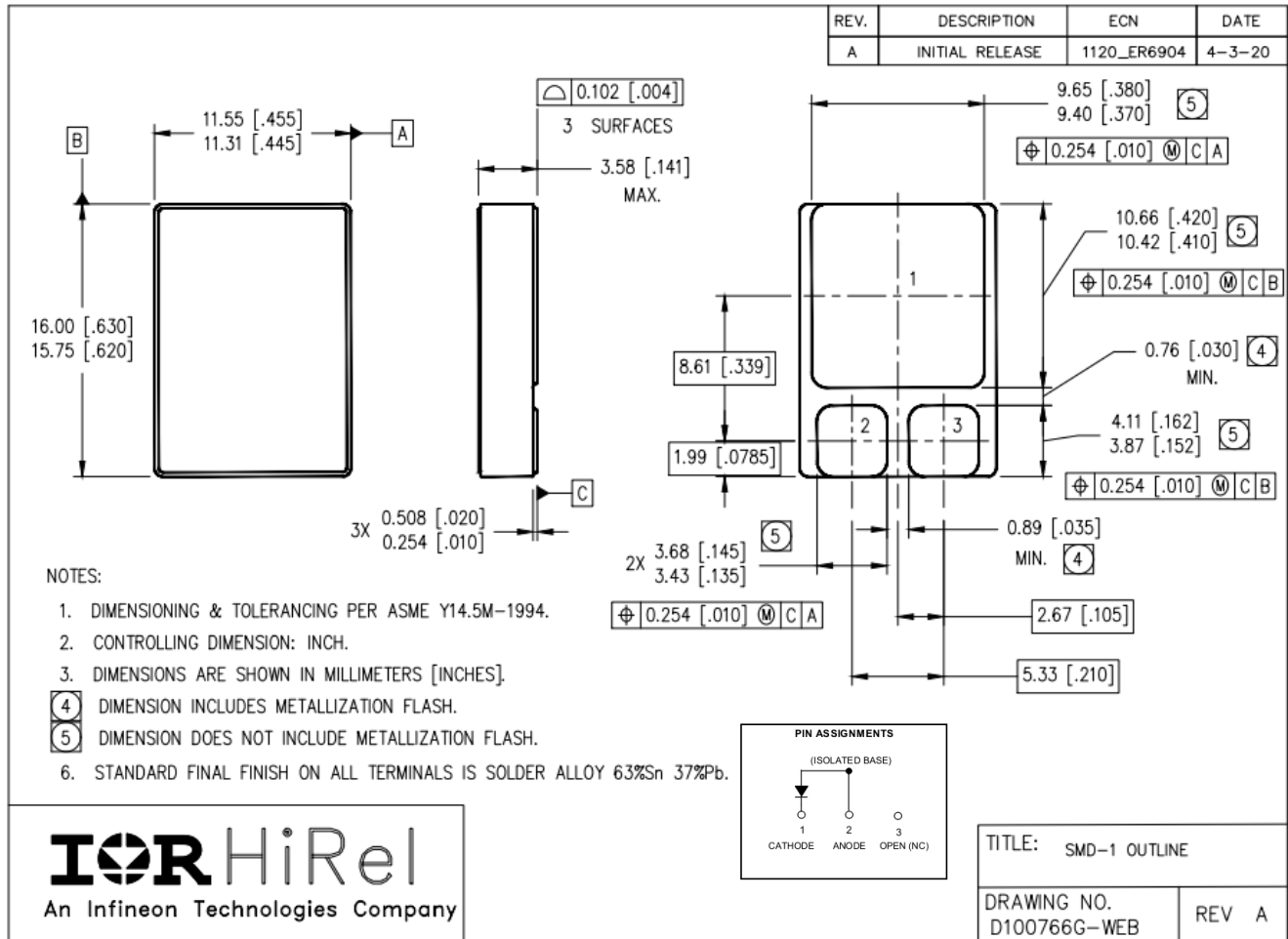
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## FRED Ultrafast, Soft Recovery Diode

### Package Outline

## 5 Package Outline

**Note:** For the most updated package outline, please see the website: [SMD-1](#)



**Revision history**

Document version	Date of release	Description of changes
	6/30/1999	Final datasheet (PD-20381)
Rev A	04/10/2010	Updated per ECN-17456
Rev B	03/04/2013	Updated per ECN-1120-0911
Rev C	10/14/2016	Updated per ECN-1120-04754
Rev D	06/02/2022	Updated per ECN-1120-08972

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**Email: [erratum@infineon.com](mailto:erratum@infineon.com)**

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